



Welcome to [E-XFL.COM](https://www.e-xfl.com)

### Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

### Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

#### Details

Product Status	Active
Number of LABs/CLBs	250540
Number of Logic Elements/Cells	660000
Total RAM Bits	49610752
Number of I/O	696
Number of Gates	-
Voltage - Supply	0.87V ~ 0.93V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	1517-BBGA, FCBGA
Supplier Device Package	1517-FCBGA (40x40)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/intel/10ax066k4f40i3sg">https://www.e-xfl.com/product-detail/intel/10ax066k4f40i3sg</a>



## Key Advantages of Intel Arria 10 Devices

**Table 2. Key Advantages of the Intel Arria 10 Device Family**

Advantage	Supporting Feature
Enhanced core architecture	<ul style="list-style-type: none"><li>Built on TSMC's 20 nm process technology</li><li>60% higher performance than the previous generation of mid-range FPGAs</li><li>15% higher performance than the fastest previous-generation FPGA</li></ul>
High-bandwidth integrated transceivers	<ul style="list-style-type: none"><li>Short-reach rates up to 25.8 Gigabits per second (Gbps)</li><li>Backplane capability up to 12.5 Gbps</li><li>Integrated 10GBASE-KR and 40GBASE-KR4 Forward Error Correction (FEC)</li></ul>
Improved logic integration and hard IP blocks	<ul style="list-style-type: none"><li>8-input adaptive logic module (ALM)</li><li>Up to 65.6 megabits (Mb) of embedded memory</li><li>Variable-precision digital signal processing (DSP) blocks</li><li>Fractional synthesis phase-locked loops (PLLs)</li><li>Hard PCI Express Gen3 IP blocks</li><li>Hard memory controllers and PHY up to 2,400 Megabits per second (Mbps)</li></ul>
Second generation hard processor system (HPS) with integrated ARM* Cortex*-A9* MPCore* processor	<ul style="list-style-type: none"><li>Tight integration of a dual-core ARM Cortex-A9 MPCore processor, hard IP, and an FPGA in a single Intel Arria 10 system-on-a-chip (SoC)</li><li>Supports over 128 Gbps peak bandwidth with integrated data coherency between the processor and the FPGA fabric</li></ul>
Advanced power savings	<ul style="list-style-type: none"><li>Comprehensive set of advanced power saving features</li><li>Power-optimized MultiTrack routing and core architecture</li><li>Up to 40% lower power compared to previous generation of mid-range FPGAs</li><li>Up to 60% lower power compared to previous generation of high-end FPGAs</li></ul>

## Summary of Intel Arria 10 Features

**Table 3. Summary of Features for Intel Arria 10 Devices**

Feature	Description
Technology	<ul style="list-style-type: none"><li>TSMC's 20-nm SoC process technology</li><li>Allows operation at a lower <math>V_{CC}</math> level of 0.82 V instead of the 0.9 V standard <math>V_{CC}</math> core voltage</li></ul>
Packaging	<ul style="list-style-type: none"><li>1.0 mm ball-pitch FINELINE BGA packaging</li><li>0.8 mm ball-pitch Ultra FINELINE BGA packaging</li><li>Multiple devices with identical package footprints for seamless migration between different FPGA densities</li><li>Devices with compatible package footprints allow migration to next generation high-end Stratix® 10 devices</li><li>RoHS, leaded<sup>(1)</sup>, and lead-free (Pb-free) options</li></ul>
High-performance FPGA fabric	<ul style="list-style-type: none"><li>Enhanced 8-input ALM with four registers</li><li>Improved multi-track routing architecture to reduce congestion and improve compilation time</li><li>Hierarchical core clocking architecture</li><li>Fine-grained partial reconfiguration</li></ul>
Internal memory blocks	<ul style="list-style-type: none"><li>M20K—20-Kb memory blocks with hard error correction code (ECC)</li><li>Memory logic array block (MLAB)—640-bit memory</li></ul>
continued...	

(1) Contact Intel for availability.



Feature	Description	
Embedded Hard IP blocks	Variable-precision DSP	<ul style="list-style-type: none"><li>Native support for signal processing precision levels from 18 x 19 to 54 x 54</li><li>Native support for 27 x 27 multiplier mode</li><li>64-bit accumulator and cascade for systolic finite impulse responses (FIRs)</li><li>Internal coefficient memory banks</li><li>Preadder/subtractor for improved efficiency</li><li>Additional pipeline register to increase performance and reduce power</li><li>Supports floating point arithmetic:<ul style="list-style-type: none"><li>Perform multiplication, addition, subtraction, multiply-add, multiply-subtract, and complex multiplication.</li><li>Supports multiplication with accumulation capability, cascade summation, and cascade subtraction capability.</li><li>Dynamic accumulator reset control.</li><li>Support direct vector dot and complex multiplication chaining multiply floating point DSP blocks.</li></ul></li></ul>
	Memory controller	DDR4, DDR3, and DDR3L
	PCI Express*	PCI Express (PCIe*) Gen3 (x1, x2, x4, or x8), Gen2 (x1, x2, x4, or x8) and Gen1 (x1, x2, x4, or x8) hard IP with complete protocol stack, endpoint, and root port
	Transceiver I/O	<ul style="list-style-type: none"><li>10GBASE-KR/40GBASE-KR4 Forward Error Correction (FEC)</li><li>PCS hard IPs that support:<ul style="list-style-type: none"><li>10-Gbps Ethernet (10GbE)</li><li>PCIe PIPE interface</li><li>Interlaken</li><li>Gbps Ethernet (GbE)</li><li>Common Public Radio Interface (CPRI) with deterministic latency support</li><li>Gigabit-capable passive optical network (GPON) with fast lock-time support</li></ul></li><li>13.5G JESD204b</li><li>8B/10B, 64B/66B, 64B/67B encoders and decoders</li><li>Custom mode support for proprietary protocols</li></ul>
Core clock networks	<ul style="list-style-type: none"><li>Up to 800 MHz fabric clocking, depending on the application:<ul style="list-style-type: none"><li>667 MHz external memory interface clocking with 2,400 Mbps DDR4 interface</li><li>800 MHz LVDS interface clocking with 1,600 Mbps LVDS interface</li></ul></li><li>Global, regional, and peripheral clock networks</li><li>Clock networks that are not used can be gated to reduce dynamic power</li></ul>	
Phase-locked loops (PLLs)	<ul style="list-style-type: none"><li>High-resolution fractional synthesis PLLs:<ul style="list-style-type: none"><li>Precision clock synthesis, clock delay compensation, and zero delay buffering (ZDB)</li><li>Support integer mode and fractional mode</li><li>Fractional mode support with third-order delta-sigma modulation</li></ul></li><li>Integer PLLs:<ul style="list-style-type: none"><li>Adjacent to general purpose I/Os</li><li>Support external memory and LVDS interfaces</li></ul></li></ul>	
FPGA General-purpose I/Os (GPIOs)	<ul style="list-style-type: none"><li>1.6 Gbps LVDS—every pair can be configured as receiver or transmitter</li><li>On-chip termination (OCT)</li><li>1.2 V to 3.0 V single-ended LVTTTL/LVCMOS interfacing</li></ul>	
External Memory Interface	<ul style="list-style-type: none"><li>Hard memory controller—DDR4, DDR3, and DDR3L support<ul style="list-style-type: none"><li>DDR4—speeds up to 1,200 MHz/2,400 Mbps</li><li>DDR3—speeds up to 1,067 MHz/2,133 Mbps</li></ul></li><li>Soft memory controller—provides support for RLDRAM 3<sup>(2)</sup>, QDR IV<sup>(2)</sup>, and QDR II+</li></ul>	
continued...		



Feature	Description	
Low-power serial transceivers	<ul style="list-style-type: none"><li>Continuous operating range:<ul style="list-style-type: none"><li>Intel Arria 10 GX—1 Gbps to 17.4 Gbps</li><li>Intel Arria 10 GT—1 Gbps to 25.8 Gbps</li></ul></li><li>Backplane support:<ul style="list-style-type: none"><li>Intel Arria 10 GX—up to 12.5</li><li>Intel Arria 10 GT—up to 12.5</li></ul></li><li>Extended range down to 125 Mbps with oversampling</li><li>ATX transmit PLLs with user-configurable fractional synthesis capability</li><li>Electronic Dispersion Compensation (EDC) support for XFP, SFP+, QSFP, and CFP optical module</li><li>Adaptive linear and decision feedback equalization</li><li>Transmitter pre-emphasis and de-emphasis</li><li>Dynamic partial reconfiguration of individual transceiver channels</li></ul>	
HPS (Intel Arria 10 SX devices only)	Processor and system	<ul style="list-style-type: none"><li>Dual-core ARM Cortex-A9 MPCore processor—1.2 GHz CPU with 1.5 GHz overdrive capability</li><li>256 KB on-chip RAM and 64 KB on-chip ROM</li><li>System peripherals—general-purpose timers, watchdog timers, direct memory access (DMA) controller, FPGA configuration manager, and clock and reset managers</li><li>Security features—anti-tamper, secure boot, Advanced Encryption Standard (AES) and authentication (SHA)</li><li>ARM CoreSight* JTAG debug access port, trace port, and on-chip trace storage</li></ul>
	External interfaces	<ul style="list-style-type: none"><li>Hard memory interface—Hard memory controller (2,400 Mbps DDR4, and 2,133 Mbps DDR3), Quad serial peripheral interface (QSPI) flash controller, NAND flash controller, direct memory access (DMA) controller, Secure Digital/MultiMediaCard (SD/MMC) controller</li><li>Communication interface— 10/100/1000 Ethernet media access control (MAC), USB On-The-Go (OTG) controllers, I<sup>2</sup>C controllers, UART 16550, serial peripheral interface (SPI), and up to 62 HPS GPIO interfaces (48 direct-share I/Os)</li></ul>
	Interconnects to core	<ul style="list-style-type: none"><li>High-performance ARM AMBA* AXI bus bridges that support simultaneous read and write</li><li>HPS-FPGA bridges—include the FPGA-to-HPS, HPS-to-FPGA, and lightweight HPS-to-FPGA bridges that allow the FPGA fabric to issue transactions to slaves in the HPS, and vice versa</li><li>Configuration bridge that allows HPS configuration manager to configure the core logic via dedicated 32-bit configuration port</li><li>FPGA-to-HPS SDRAM controller bridge—provides configuration interfaces for the multiport front end (MPFE) of the HPS SDRAM controller</li></ul>
Configuration	<ul style="list-style-type: none"><li>Tamper protection—comprehensive design protection to protect your valuable IP investments</li><li>Enhanced 256-bit advanced encryption standard (AES) design security with authentication</li><li>Configuration via protocol (CvP) using PCIe Gen1, Gen2, or Gen3</li></ul>	
continued...		

(2) Intel Arria 10 devices support this external memory interface using hard PHY with soft memory controller.



## Maximum Resources

**Table 5. Maximum Resource Counts for Intel Arria 10 GX Devices (GX 160, GX 220, GX 270, GX 320, and GX 480)**

Resource		Product Line				
		GX 160	GX 220	GX 270	GX 320	GX 480
Logic Elements (LE) (K)		160	220	270	320	480
ALM		61,510	80,330	101,620	119,900	183,590
Register		246,040	321,320	406,480	479,600	734,360
Memory (Kb)	M20K	8,800	11,740	15,000	17,820	28,620
	MLAB	1,050	1,690	2,452	2,727	4,164
Variable-precision DSP Block		156	192	830	985	1,368
18 x 19 Multiplier		312	384	1,660	1,970	2,736
PLL	Fractional Synthesis	6	6	8	8	12
	I/O	6	6	8	8	12
17.4 Gbps Transceiver		12	12	24	24	36
GPIO <sup>(3)</sup>		288	288	384	384	492
LVDS Pair <sup>(4)</sup>		120	120	168	168	222
PCIe Hard IP Block		1	1	2	2	2
Hard Memory Controller		6	6	8	8	12

<sup>(3)</sup> The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

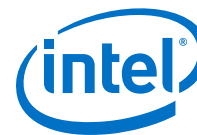
<sup>(4)</sup> Each LVDS I/O pair can be used as differential input or output.



## Available Options

Figure 2. Sample Ordering Code and Available Options for Intel Arria 10 GT Devices





## Maximum Resources

**Table 12. Maximum Resource Counts for Intel Arria 10 SX Devices**

Resource		Product Line						
		SX 160	SX 220	SX 270	SX 320	SX 480	SX 570	SX 660
Logic Elements (LE) (K)		160	220	270	320	480	570	660
ALM		61,510	80,330	101,620	119,900	183,590	217,080	251,680
Register		246,040	321,320	406,480	479,600	734,360	868,320	1,006,720
Memory (Kb)	M20K	8,800	11,740	15,000	17,820	28,620	36,000	42,620
	MLAB	1,050	1,690	2,452	2,727	4,164	5,096	5,788
Variable-precision DSP Block		156	192	830	985	1,368	1,523	1,687
18 x 19 Multiplier		312	384	1,660	1,970	2,736	3,046	3,374
PLL	Fractional Synthesis	6	6	8	8	12	16	16
	I/O	6	6	8	8	12	16	16
17.4 Gbps Transceiver		12	12	24	24	36	48	48
GPIO <sup>(8)</sup>		288	288	384	384	492	696	696
LVDS Pair <sup>(9)</sup>		120	120	168	168	174	324	324
PCIe Hard IP Block		1	1	2	2	2	2	2
Hard Memory Controller		6	6	8	8	12	16	16
ARM Cortex-A9 MPCore Processor		Yes	Yes	Yes	Yes	Yes	Yes	Yes

## Package Plan

**Table 13. Package Plan for Intel Arria 10 SX Devices (U19, F27, F29, and F34)**

Refer to I/O and High Speed I/O in Intel Arria 10 Devices chapter for the number of 3 V I/O, LVDS I/O, and LVDS channels in each device package.

Product Line	U19 (19 mm × 19 mm, 484-pin UBGGA)			F27 (27 mm × 27 mm, 672-pin FBGA)			F29 (29 mm × 29 mm, 780-pin FBGA)			F34 (35 mm × 35 mm, 1152-pin FBGA)		
	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR
SX 160	48	144	6	48	192	12	48	240	12	—	—	—
SX 220	48	144	6	48	192	12	48	240	12	—	—	—
SX 270	—	—	—	48	192	12	48	312	12	48	336	24
SX 320	—	—	—	48	192	12	48	312	12	48	336	24
continued...												

<sup>(8)</sup> The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

<sup>(9)</sup> Each LVDS I/O pair can be used as differential input or output.



Product Line	U19 (19 mm × 19 mm, 484-pin UBGA)			F27 (27 mm × 27 mm, 672-pin FBGA)			F29 (29 mm × 29 mm, 780-pin FBGA)			F34 (35 mm × 35 mm, 1152-pin FBGA)		
	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR
SX 480	—	—	—	—	—	—	48	312	12	48	444	24
SX 570	—	—	—	—	—	—	—	—	—	48	444	24
SX 660	—	—	—	—	—	—	—	—	—	48	444	24

**Table 14. Package Plan for Intel Arria 10 SX Devices (F35, KF40, and NF40)**

Refer to I/O and High Speed I/O in Intel Arria 10 Devices chapter for the number of 3 V I/O, LVDS I/O, and LVDS channels in each device package.

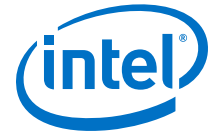
Product Line	F35 (35 mm × 35 mm, 1152-pin FBGA)			KF40 (40 mm × 40 mm, 1517-pin FBGA)			NF40 (40 mm × 40 mm, 1517-pin FBGA)		
	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR
SX 270	48	336	24	—	—	—	—	—	—
SX 320	48	336	24	—	—	—	—	—	—
SX 480	48	348	36	—	—	—	—	—	—
SX 570	48	348	36	96	600	36	48	540	48
SX 660	48	348	36	96	600	36	48	540	48

#### Related Information

[I/O and High-Speed Differential I/O Interfaces in Intel Arria 10 Devices chapter, Intel Arria 10 Device Handbook](#)

Provides the number of 3 V and LVDS I/Os, and LVDS channels for each Intel Arria 10 device package.





## I/O Vertical Migration for Intel Arria 10 Devices

**Figure 4. Migration Capability Across Intel Arria 10 Product Lines**

- The arrows indicate the migration paths. The devices included in each vertical migration path are shaded. Devices with fewer resources in the same path have lighter shades.
- To achieve the full I/O migration across product lines in the same migration path, restrict I/Os and transceivers usage to match the product line with the lowest I/O and transceiver counts.
- An LVDS I/O bank in the source device may be mapped to a 3 V I/O bank in the target device. To use memory interface clock frequency higher than 533 MHz, assign external memory interface pins only to banks that are LVDS I/O in both devices.
- There may be nominal 0.15 mm package height difference between some product lines in the same package type.
- Some migration paths are not shown in the Intel Quartus Prime software **Pin Migration View**.

Variant	Product Line	Package										
		U19	F27	F29	F34	F35	KF40	NF40	RF40	NF45	SF45	UF45
Intel® Arria® 10 GX	GX 160	↑	↑	↑								
	GX 220	↓	↓	↓								
	GX 270		↓	↓	↑	↑						
	GX 320		↓	↓	↑	↑						
	GX 480			↓	↑	↑						
	GX 570				↑	↑	↑	↑				
	GX 660				↑	↑	↑	↑	↑	↑	↑	↑
	GX 900				↑			↑	↑	↑	↑	↑
	GX 1150				↑			↑	↑	↑	↑	↑
	GT 900										↑	↑
	GT 1150										↑	↑
Intel Arria 10 SX	SX 160	↑	↑	↑								
	SX 220	↓	↓	↓								
	SX 270		↓	↓	↑	↑						
	SX 320		↓	↓	↑	↑						
	SX 480			↓	↑	↑						
	SX 570				↑	↑	↑	↑				
	SX 660				↑	↑	↑	↑				

**Note:** To verify the pin migration compatibility, use the **Pin Migration View** window in the Intel Quartus Prime software Pin Planner.

## Adaptive Logic Module

Intel Arria 10 devices use a 20 nm ALM as the basic building block of the logic fabric.

The ALM architecture is the same as the previous generation FPGAs, allowing for efficient implementation of logic functions and easy conversion of IP between the device generations.

The ALM, as shown in following figure, uses an 8-input fracturable look-up table (LUT) with four dedicated registers to help improve timing closure in register-rich designs and achieve an even higher design packing capability than the traditional two-register per LUT architecture.



Features for floating-point arithmetic:

- A completely hardened architecture that supports multiplication, addition, subtraction, multiply-add, and multiply-subtract
- Multiplication with accumulation capability and a dynamic accumulator reset control
- Multiplication with cascade summation capability
- Multiplication with cascade subtraction capability
- Complex multiplication
- Direct vector dot product
- Systolic FIR filter

**Table 15. Variable-Precision DSP Block Configurations for Intel Arria 10 Devices**

Usage Example	Multiplier Size (Bit)	DSP Block Resources
Medium precision fixed point	Two 18 x 19	1
High precision fixed or Single precision floating point	One 27 x 27	1
Fixed point FFTs	One 19 x 36 with external adder	1
Very high precision fixed point	One 36 x 36 with external adder	2
Double precision floating point	One 54 x 54 with external adder	4

**Table 16. Resources for Fixed-Point Arithmetic in Intel Arria 10 Devices**

The table lists the variable-precision DSP resources by bit precision for each Intel Arria 10 device.

Variant	Product Line	Variable-precision DSP Block	Independent Input and Output Multiplications Operator		18 x 19 Multiplier Adder Sum Mode	18 x 18 Multiplier Adder Summed with 36 bit Input
			18 x 19 Multiplier	27 x 27 Multiplier		
Intel Arria 10 GX	GX 160	156	312	156	156	156
	GX 220	192	384	192	192	192
	GX 270	830	1,660	830	830	830
	GX 320	984	1,968	984	984	984
	GX 480	1,368	2,736	1,368	1,368	1,368
	GX 570	1,523	3,046	1,523	1,523	1,523
	GX 660	1,687	3,374	1,687	1,687	1,687
	GX 900	1,518	3,036	1,518	1,518	1,518
	GX 1150	1,518	3,036	1,518	1,518	1,518
Intel Arria 10 GT	GT 900	1,518	3,036	1,518	1,518	1,518
	GT 1150	1,518	3,036	1,518	1,518	1,518
Intel Arria 10 SX	SX 160	156	312	156	156	156
	SX 220	192	384	192	192	192
	SX 270	830	1,660	830	830	830

*continued...*



## Types of Embedded Memory

The Intel Arria 10 devices contain two types of memory blocks:

- 20 Kb M20K blocks—blocks of dedicated memory resources. The M20K blocks are ideal for larger memory arrays while still providing a large number of independent ports.
- 640 bit memory logic array blocks (MLABs)—enhanced memory blocks that are configured from dual-purpose logic array blocks (LABs). The MLABs are ideal for wide and shallow memory arrays. The MLABs are optimized for implementation of shift registers for digital signal processing (DSP) applications, wide and shallow FIFO buffers, and filter delay lines. Each MLAB is made up of ten adaptive logic modules (ALMs). In the Intel Arria 10 devices, you can configure these ALMs as ten 32 x 2 blocks, giving you one 32 x 20 simple dual-port SRAM block per MLAB.

## Embedded Memory Capacity in Intel Arria 10 Devices

**Table 18. Embedded Memory Capacity and Distribution in Intel Arria 10 Devices**

Variant	Product Line	M20K		MLAB		Total RAM Bit (Kb)
		Block	RAM Bit (Kb)	Block	RAM Bit (Kb)	
Intel Arria 10 GX	GX 160	440	8,800	1,680	1,050	9,850
	GX 220	587	11,740	2,703	1,690	13,430
	GX 270	750	15,000	3,922	2,452	17,452
	GX 320	891	17,820	4,363	2,727	20,547
	GX 480	1,431	28,620	6,662	4,164	32,784
	GX 570	1,800	36,000	8,153	5,096	41,096
	GX 660	2,131	42,620	9,260	5,788	48,408
	GX 900	2,423	48,460	15,017	9,386	57,846
	GX 1150	2,713	54,260	20,774	12,984	67,244
Intel Arria 10 GT	GT 900	2,423	48,460	15,017	9,386	57,846
	GT 1150	2,713	54,260	20,774	12,984	67,244
Intel Arria 10 SX	SX 160	440	8,800	1,680	1,050	9,850
	SX 220	587	11,740	2,703	1,690	13,430
	SX 270	750	15,000	3,922	2,452	17,452
	SX 320	891	17,820	4,363	2,727	20,547
	SX 480	1,431	28,620	6,662	4,164	32,784
	SX 570	1,800	36,000	8,153	5,096	41,096
	SX 660	2,131	42,620	9,260	5,788	48,408

**Table 20. Memory Standards Supported by the Hard Memory Controller**

This table lists the overall capability of the hard memory controller. For specific details, refer to the External Memory Interface Spec Estimator and Intel Arria 10 Device Datasheet.

Memory Standard	Rate Support	Ping Pong PHY Support	Maximum Frequency (MHz)
DDR4 SDRAM	Quarter rate	Yes	1,067
		—	1,200
DDR3 SDRAM	Half rate	Yes	533
		—	667
	Quarter rate	Yes	1,067
		—	1,067
DDR3L SDRAM	Half rate	Yes	533
		—	667
	Quarter rate	Yes	933
		—	933
LPDDR3 SDRAM	Half rate	—	533
	Quarter rate	—	800

**Table 21. Memory Standards Supported by the Soft Memory Controller**

Memory Standard	Rate Support	Maximum Frequency (MHz)
RLDRAM 3 <sup>(11)</sup>	Quarter rate	1,200
QDR IV SRAM <sup>(11)</sup>	Quarter rate	1,067
QDR II SRAM	Full rate	333
	Half rate	633
QDR II+ SRAM	Full rate	333
	Half rate	633
QDR II+ Xtreme SRAM	Full rate	333
	Half rate	633

**Table 22. Memory Standards Supported by the HPS Hard Memory Controller**

The hard processor system (HPS) is available in Intel Arria 10 SoC devices only.

Memory Standard	Rate Support	Maximum Frequency (MHz)
DDR4 SDRAM	Half rate	1,200
DDR3 SDRAM	Half rate	1,067
DDR3L SDRAM	Half rate	933

<sup>(11)</sup> Intel Arria 10 devices support this external memory interface using hard PHY with soft memory controller.



### **Related Information**

#### [Intel Arria 10 Device Datasheet](#)

Lists the memory interface performance according to memory interface standards, rank or chip select configurations, and Intel Arria 10 device speed grades.

## **PCIe Gen1, Gen2, and Gen3 Hard IP**

Intel Arria 10 devices contain PCIe hard IP that is designed for performance and ease-of-use:

- Includes all layers of the PCIe stack—transaction, data link and physical layers.
- Supports PCIe Gen3, Gen2, and Gen1 Endpoint and Root Port in x1, x2, x4, or x8 lane configuration.
- Operates independently from the core logic—optional configuration via protocol (CvP) allows the PCIe link to power up and complete link training in less than 100 ms while the Intel Arria 10 device completes loading the programming file for the rest of the FPGA.
- Provides added functionality that makes it easier to support emerging features such as Single Root I/O Virtualization (SR-IOV) and optional protocol extensions.
- Provides improved end-to-end datapath protection using ECC.
- Supports FPGA configuration via protocol (CvP) using PCIe at Gen3, Gen2, or Gen1 speed.

### **Related Information**

[PCS Features](#) on page 30

## **Enhanced PCS Hard IP for Interlaken and 10 Gbps Ethernet**

### **Interlaken Support**

The Intel Arria 10 enhanced PCS hard IP provides integrated Interlaken PCS supporting rates up to 25.8 Gbps per lane.

The Interlaken PCS is based on the proven functionality of the PCS developed for Intel's previous generation FPGAs, which demonstrated interoperability with Interlaken ASSP vendors and third-party IP suppliers. The Interlaken PCS is present in every transceiver channel in Intel Arria 10 devices.

### **Related Information**

[PCS Features](#) on page 30

### **10 Gbps Ethernet Support**

The Intel Arria 10 enhanced PCS hard IP supports 10GBASE-R PCS compliant with IEEE 802.3 10 Gbps Ethernet (10GbE). The integrated hard IP support for 10GbE and the 10 Gbps transceivers save external PHY cost, board space, and system power.



The scalable hard IP supports multiple independent 10GbE ports while using a single PLL for all the 10GBASE-R PCS instantiations, which saves on core logic resources and clock networks:

- Simplifies multiport 10GbE systems compared to XAUI interfaces that require an external XAUI-to-10G PHY.
- Incorporates Electronic Dispersion Compensation (EDC), which enables direct connection to standard 10 Gbps XFP and SFP+ pluggable optical modules.
- Supports backplane Ethernet applications and includes a hard 10GBASE-KR Forward Error Correction (FEC) circuit that you can use for 10 Gbps and 40 Gbps applications.

The 10 Gbps Ethernet PCS hard IP and 10GBASE-KR FEC are present in every transceiver channel.

#### **Related Information**

[PCS Features](#) on page 30

## **Low Power Serial Transceivers**

Intel Arria 10 FPGAs and SoCs include lowest power transceivers that deliver high bandwidth, throughput and low latency.

Intel Arria 10 devices deliver the industry's lowest power consumption per transceiver channel:

- 12.5 Gbps transceivers at as low as 242 mW
- 10 Gbps transceivers at as low as 168 mW
- 6 Gbps transceivers at as low as 117 mW

Intel Arria 10 transceivers support various data rates according to application:

- Chip-to-chip and chip-to-module applications—from 1 Gbps up to 25.8 Gbps
- Long reach and backplane applications—from 1 Gbps up to 12.5 with advanced adaptive equalization
- Critical power sensitive applications—from 1 Gbps up to 11.3 Gbps using lower power modes

The combination of 20 nm process technology and architectural advances provide the following benefits:

- Significant reduction in die area and power consumption
- Increase of up to two times in transceiver I/O density compared to previous generation devices while maintaining optimal signal integrity
- Up to 72 total transceiver channels—you can configure up to 6 of these channels to run as fast as 25.8 Gbps
- All channels feature continuous data rate support up to the maximum rated speed

Figure 6. Intel Arria 10 Transceiver Block Architecture



## Transceiver Channels

All transceiver channels feature a dedicated Physical Medium Attachment (PMA) and a hardened Physical Coding Sublayer (PCS).

- The PMA provides primary interfacing capabilities to physical channels.
- The PCS typically handles encoding/decoding, word alignment, and other pre-processing functions before transferring data to the FPGA core fabric.

A transceiver channel consists of a PMA and a PCS block. Most transceiver banks have 6 channels. There are some transceiver banks that contain only 3 channels.

A wide variety of bonded and non-bonded data rate configurations is possible using a highly configurable clock distribution network. Up to 80 independent transceiver data rates can be configured.

The following figures are graphical representations of top views of the silicon die, which correspond to reverse views for flip chip packages. Different Intel Arria 10 devices may have different floorplans than the ones shown in the figures.



Protocol	Data Rate (Gbps)	Transceiver IP	PCS Support
CPRI 6.0 (64B/66B)	0.6144 to 10.1376	Native PHY	Enhanced PCS
CPRI 4.2 (8B/10B)	0.6144 to 9.8304	Native PHY	Standard PCS
OBSAI RP3 v4.2	0.6144 to 6.144	Native PHY	Standard PCS
SD-SDI/HD-SDI/3G-SDI	0.143 <sup>(12)</sup> to 2.97	Native PHY	Standard PCS

### Related Information

#### [Intel Arria 10 Transceiver PHY User Guide](#)

Provides more information about the supported transceiver protocols and PHY IP, the PMA architecture, and the standard, enhanced, and PCIe Gen3 PCS architecture.

## SoC with Hard Processor System

Each SoC device combines an FPGA fabric and a hard processor system (HPS) in a single device. This combination delivers the flexibility of programmable logic with the power and cost savings of hard IP in these ways:

- Reduces board space, system power, and bill of materials cost by eliminating a discrete embedded processor
- Allows you to differentiate the end product in both hardware and software, and to support virtually any interface standard
- Extends the product life and revenue through in-field hardware and software updates

---

<sup>(12)</sup> The 0.143 Gbps data rate is supported using oversampling of user logic that you must implement in the FPGA fabric.





## Features of the HPS

The HPS has the following features:

- 1.2-GHz, dual-core ARM Cortex-A9 MPCore processor with up to 1.5-GHz via overdrive
  - ARMv7-A architecture that runs 32-bit ARM instructions, 16-bit and 32-bit Thumb instructions, and 8-bit Java byte codes in Jazelle style
  - Superscalar, variable length, out-of-order pipeline with dynamic branch prediction
  - Instruction Efficiency 2.5 MIPS/MHz, which provides total performance of 7500 MIPS at 1.5 GHz
- Each processor core includes:
  - 32 KB of L1 instruction cache, 32 KB of L1 data cache
  - Single- and double-precision floating-point unit and NEON media engine
  - CoreSight debug and trace technology
  - Snoop Control Unit (SCU) and Acceleration Coherency Port (ACP)
- 512 KB of shared L2 cache
- 256 KB of scratch RAM
- Hard memory controller with support for DDR3, DDR4 and optional error correction code (ECC) support
- Multiport Front End (MPFE) Scheduler interface to the hard memory controller
- 8-channel direct memory access (DMA) controller
- QSPI flash controller with SIO, DIO, QIO SPI Flash support
- NAND flash controller (ONFI 1.0 or later) with DMA and ECC support, updated to support 8 and 16-bit Flash devices and new command DMA to offload CPU for fast power down recovery
- Updated SD/SDIO/MMC controller to eMMC 4.5 with DMA with CE-ATA digital command support
- 3 10/100/1000 Ethernet media access control (MAC) with DMA
- 2 USB On-the-Go (OTG) controllers with DMA
- 5 I<sup>2</sup>C controllers (3 can be used by EMAC for MIO to external PHY)
- 2 UART 16550 Compatible controllers
- 4 serial peripheral interfaces (SPI) (2 Master, 2 Slaves)
- 62 programmable general-purpose I/Os, which includes 48 direct share I/Os that allows the HPS peripherals to connect directly to the FPGA I/Os
- 7 general-purpose timers
- 4 watchdog timers
- Anti-tamper, Secure Boot, Encryption (AES) and Authentication (SHA)

## System Peripherals and Debug Access Port

Each Ethernet MAC, USB OTG, NAND flash controller, and SD/MMC controller module has an integrated DMA controller. For modules without an integrated DMA controller, an additional DMA controller module provides up to eight channels of high-bandwidth data transfers. Peripherals that communicate off-chip are multiplexed with other peripherals at the HPS pin level. This allows you to choose which peripherals interface with other devices on your PCB.

The debug access port provides interfaces to industry standard JTAG debug probes and supports ARM CoreSight debug and core traces to facilitate software development.

## HPS-FPGA AXI Bridges

The HPS-FPGA bridges, which support the Advanced Microcontroller Bus Architecture (AMBA) Advanced eXtensible Interface (AXI™) specifications, consist of the following bridges:

- FPGA-to-HPS AMBA AXI bridge—a high-performance bus supporting 32, 64, and 128 bit data widths that allows the FPGA fabric to issue transactions to slaves in the HPS.
- HPS-to-FPGA Avalon/AMBA AXI bridge—a high-performance bus supporting 32, 64, and 128 bit data widths that allows the HPS to issue transactions to slaves in the FPGA fabric.
- Lightweight HPS-to-FPGA AXI bridge—a lower latency 32 bit width bus that allows the HPS to issue transactions to soft peripherals in the FPGA fabric. This bridge is primarily used for control and status register (CSR) accesses to peripherals in the FPGA fabric.

The HPS-FPGA AXI bridges allow masters in the FPGA fabric to communicate with slaves in the HPS logic, and vice versa. For example, the HPS-to-FPGA AXI bridge allows you to share memories instantiated in the FPGA fabric with one or both microprocessors in the HPS, while the FPGA-to-HPS AXI bridge allows logic in the FPGA fabric to access the memory and peripherals in the HPS.

Each HPS-FPGA bridge also provides asynchronous clock crossing for data transferred between the FPGA fabric and the HPS.

## HPS SDRAM Controller Subsystem

The HPS SDRAM controller subsystem contains a multiport SDRAM controller and DDR PHY that are shared between the FPGA fabric (through the FPGA-to-HPS SDRAM interface), the level 2 (L2) cache, and the level 3 (L3) system interconnect. The FPGA-to-HPS SDRAM interface supports AMBA AXI and Avalon® Memory-Mapped (Avalon-MM) interface standards, and provides up to six individual ports for access by masters implemented in the FPGA fabric.

The HPS SDRAM controller supports up to 3 masters (command ports), 3x 64-bit read data ports and 3x 64-bit write data ports.

To maximize memory performance, the SDRAM controller subsystem supports command and data reordering, deficit round-robin arbitration with aging, and high-priority bypass features.



## FPGA Configuration and HPS Booting

The FPGA fabric and HPS in the SoC FPGA must be powered at the same time. You can reduce the clock frequencies or gate the clocks to reduce dynamic power.

Once powered, the FPGA fabric and HPS can be configured independently thus providing you with more design flexibility:

- You can boot the HPS independently. After the HPS is running, the HPS can fully or partially reconfigure the FPGA fabric at any time under software control. The HPS can also configure other FPGAs on the board through the FPGA configuration controller.
- Configure the FPGA fabric first, and then boot the HPS from memory accessible to the FPGA fabric.

## Hardware and Software Development

For hardware development, you can configure the HPS and connect your soft logic in the FPGA fabric to the HPS interfaces using the Platform Designer system integration tool in the Intel Quartus Prime software.

For software development, the ARM-based SoC FPGA devices inherit the rich software development ecosystem available for the ARM Cortex-A9 MPCore processor. The software development process for Intel SoC FPGAs follows the same steps as those for other SoC devices from other manufacturers. Support for Linux\*, VxWorks\*, and other operating systems are available for the SoC FPGAs. For more information on the operating systems support availability, contact the Intel FPGA sales team.

You can begin device-specific firmware and software development on the Intel SoC FPGA Virtual Target. The Virtual Target is a fast PC-based functional simulation of a target development system—a model of a complete development board. The Virtual Target enables the development of device-specific production software that can run unmodified on actual hardware.

## Dynamic and Partial Reconfiguration

The Intel Arria 10 devices support dynamic and partial reconfiguration. You can use dynamic and partial reconfiguration simultaneously to enable seamless reconfiguration of both the device core and transceivers.

### Dynamic Reconfiguration

You can reconfigure the PMA and PCS blocks while the device continues to operate. This feature allows you to change the data rates, protocol, and analog settings of a channel in a transceiver bank without affecting on-going data transfer in other transceiver banks. This feature is ideal for applications that require dynamic multiprotocol or multirate support.

### Partial Reconfiguration

Using partial reconfiguration, you can reconfigure some parts of the device while keeping the device in operation.



The optional power reduction techniques in Intel Arria 10 devices include:

- **SmartVID**—a code is programmed into each device during manufacturing that allows a smart regulator to operate the device at lower core  $V_{CC}$  while maintaining performance
- **Programmable Power Technology**—non-critical timing paths are identified by the Intel Quartus Prime software and the logic in these paths is biased for low power instead of high performance
- **Low Static Power Options**—devices are available with either standard static power or low static power while maintaining performance

Furthermore, Intel Arria 10 devices feature Intel's industry-leading low power transceivers and include a number of hard IP blocks that not only reduce logic resources but also deliver substantial power savings compared to soft implementations. In general, hard IP blocks consume up to 90% less power than the equivalent soft logic implementations.

## Incremental Compilation

The Intel Quartus Prime software incremental compilation feature reduces compilation time and helps preserve performance to ease timing closure. The incremental compilation feature enables the partial reconfiguration flow for Intel Arria 10 devices.

Incremental compilation supports top-down, bottom-up, and team-based design flows. This feature facilitates modular, hierarchical, and team-based design flows where different designers compile their respective design sections in parallel. Furthermore, different designers or IP providers can develop and optimize different blocks of the design independently. These blocks can then be imported into the top level project.

## Document Revision History for Intel Arria 10 Device Overview

Document Version	Changes
2018.04.09	Updated the lowest $V_{CC}$ from 0.83 V to 0.82 V in the topic listing a summary of the device features.

Date	Version	Changes
January 2018	2018.01.17	<ul style="list-style-type: none"><li>• Updated the maximum data rate for HPS (Intel Arria 10 SX devices external memory interface DDR3 controller from 2,166 Mbps to 2,133 Mbps.</li><li>• Updated maximum frequency supported for half rate QDR II and QDR II + SRAM to 633 MHz in <i>Memory Standards Supported by the Soft Memory Controller</i> table.</li><li>• Updated transceiver backplane capability to 12.5 Gbps.</li><li>• Removed transceiver speed grade 5 in <i>Sample Ordering Core and Available Options for Intel Arria 10 GX Devices</i> figure.</li></ul>
continued...		



Date	Version	Changes
August 2014	2014.08.18	<ul style="list-style-type: none"> <li>Updated Memory (Kb) M20K maximum resources for Arria 10 GX 660 devices from 42,660 to 42,620.</li> <li>Added GPIO columns consisting of LVDS I/O Bank and 3V I/O Bank in the Package Plan table.</li> <li>Added how to use memory interface clock frequency higher than 533 MHz in the I/O vertical migration.</li> <li>Added information to clarify that RLDRAM3 support uses hard PHY with soft memory controller.</li> <li>Added variable precision DSP blocks support for floating-point arithmetic.</li> </ul>
June 2014	2014.06.19	Updated number of dedicated I/Os in the HPS block to 17.
February 2014	2014.02.21	Updated transceiver speed grade options for GT devices in Figure 2.
February 2014	2014.02.06	Updated data rate for Arria 10 GT devices from 28.1 Gbps to 28.3 Gbps.
December 2013	2013.12.10	<ul style="list-style-type: none"> <li>Updated the HPS memory standards support from LPDDR2 to LPDDR3.</li> <li>Updated HPS block diagram to include dedicated HPS I/O and FPGA Configuration blocks as well as repositioned SD/SDIO/MMC, DMA, SPI and NAND Flash with ECC blocks .</li> </ul>
December 2013	2013.12.02	Initial release.